



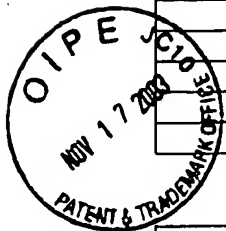
UNITED STATES PATENT AND TRADEMARK OFFICE

<p>In re application of:</p> <p>Basol et al.</p> <p>Serial No.: 10/663,318</p> <p>Filed: September 16, 2003</p> <p>Title: Conductive Structure Fabrication Process Using Novel Layered Structure And Conductive Structure Fabricated Thereby For Use In Multi-Level Metallization</p>	<p>Group Art Unit: Not yet assigned</p> <p>Examiner: Not yet assigned</p> <p>Docket: NT-108C1-US</p>
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INFORMATION DISCLOSURE STATEMENT

US PATENT DOCUMENTS

Examiner Initials	Cite No.	Document Number	Publication Date	Name of Patentee or Applicant	
TL	AA	6,191,027	Feb., 2001	Omura	In Serial No. 09/642,827
	AB	6,176,992	January, 2001	Talieh	In Serial No. 09/642,827
	AC	6,136,163	October, 2000	Cheung et al.	In Serial No. 09/642,827
	AD	6,103,085	August, 2000	Woo et al.	In Serial No. 09/642,827
	AE	6,074,544	June, 2000	Reid et al.	In Serial No. 09/642,827
	AF	6,066,030	May, 2000	Uzoh	In Serial No. 09/642,827
	AG	6,063,506	May, 2000	Andricacos et al.	In Serial No. 09/642,827
	AH	6,027,631	February, 2000	Broadbent	In Serial No. 09/642,827
	AI	6,004,880	December, 1999	Liu et al.	In Serial No. 09/642,827
	AJ	5,985,123	November, 1999	Koon	In Serial No. 09/642,827
	AK	5,954,997	September, 1999	Kaufman et al.	In Serial No. 09/642,827
	AL	5,933,753	August, 1999	Simon et al.	In Serial No. 09/642,827
	AM	5,930,669	July, 1999	Uzoh	In Serial No. 09/642,827
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	AQ	5,884,990	March, 1999	Burghartz et al.	In Serial No. 09/642,827
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	AS	5,840,629	November, 1998	Carpio	In Serial No. 09/642,827
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	AW	5,773,364	June, 1998	Farkas et al.	In Serial No. 09/642,827
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	BA	5,681,215	October, 1997	Sherwood et al.	In Serial No. 09/642,827
	BB	5,516,412	May, 1996	Andricacos et al.	In Serial No. 09/642,827
	BC	5,354,490	October, 1994	Yu et al.	In Serial No. 09/642,827
TL	BD	5,256,565	October, 1994	Bernhardt et al.	In Serial No. 09/642,827




TL	BE	5,084,071	January, 1992	Nenadic et al.	In Serial No. 09/642,827
	BF	4,975,159	December, 1990	Dahms	In Serial No. 09/642,827
	BG	4,954,142	September, 1990	Carr et al.	In Serial No. 09/642,827
	BH	4,948,474	August, 1990	Miljkovic	In Serial No. 09/642,827
	BI	4,430,173	February, 1984	Boudot et al.	In Serial No. 09/642,827
TL	BJ	3,328,273	June, 1967	Creutz et al.	In Serial No. 09/642,827

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TL	BL	WO 00/26443	May, 2000	Talieh	In Serial No. 09/642,827

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Examiner Initials	Cite No.			Translation
TL	BM	James J. Kelly et al., "Leveling and Microstructural Effects of Additives for Copper Electrodeposition", Journal of the Electrochemical Society, 146 (7), 1999, Pages 2540-2545	In Serial No. 09/642,827	
TL	BN	Joseph M. Steigerwald et al., "Chemical Mechanical Planarization of Microelectronic Materials", A Wiley-Interscience Publication, 1997 by John Wiley & Sons, Inc. pages 212-222.	In Serial No. 09/642,827	
TL	BO	Robert D. Mikkola et al., "Investigation of the Roles of the Additive Components for Second Generation Copper Electroplating Chemistries Used for Advanced Interconnect Metalization", 2000 IEEE, IEEE Electron Devices Society, Pages 117-119, June 2000	In Serial No. 09/642,827	

Examiner Signature		Date Considered	11/16/04
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